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[ON Semiconductor](#)  
[MC100LVEL12D](#)

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# MC100LVEL12

## 3.3 V ECL Low Impedance Driver

### Description

The MC100LVEL12 is a low impedance drive buffer. With two pairs of OR/NOR outputs the device is ideally suited for high drive applications such as memory addressing. The device is functionally equivalent to the EL12 device and operates from a 3.3 V power supply. With propagation delays equivalent to the EL12, the LVEL12 is ideally suited for those applications which require the ultimate in AC performance in a low voltage environment.

### Features

- 445 ps Propagation Delay
- Dual Outputs for 25 Ω Drive Applications
- ESD Protection:
  - ◆ > 4 kV Human Body Model
  - ◆ > 200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range:  $V_{CC} = 3.0\text{ V to }3.8\text{ V}$  with  $V_{EE} = 0\text{ V}$
- NECL Mode Operating Range:  $V_{CC} = 0\text{ V}$  with  $V_{EE} = -3.0\text{ V to }-3.8\text{ V}$
- Internal Input Pulldown Resistors
- Q Output will Default LOW with All Inputs Open or at  $V_{EE}$
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity:
  - ◆ Level 1 for SOIC-8
  - ◆ Level 3 for TSSOP-8
  - ◆ For Additional Information, see Application Note [AND8003/D](#)
- Flammability Rating: UL-94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 83 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



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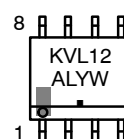


**SOIC-8**  
**D SUFFIX**  
**CASE 751**

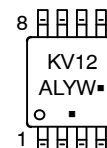


**TSSOP-8**  
**DT SUFFIX**  
**CASE 948R**

### MARKING DIAGRAMS\*



**SOIC-8**



**TSSOP-8**

- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)  
 \*For additional marking information, refer to Application Note [AND8002/D](#).

### ORDERING INFORMATION

Device	Package	Shipping
MC100LVEL12DG	SOIC-8 (Pb-Free)	98 Units / Tube
MC100LVEL12DTG	TSSOP-8 (Pb-Free)	100 Units / Tube

### MC100LVEL12

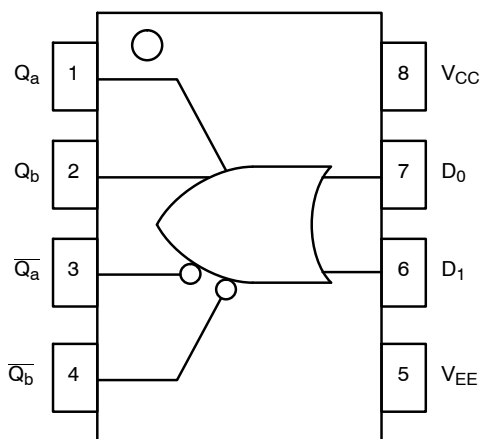


Figure 1. Logic Diagram and Pinout Assignment

Table 1. PIN DESCRIPTION

PIN	FUNCTION
D0, D1	ECL Data Inputs
Qa, Qa-bar; Qb, Qb-bar	ECL Data Outputs
V <sub>CC</sub>	Positive Supply
V <sub>EE</sub>	Negative Supply

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V <sub>CC</sub>	PECL Mode Power Supply	V <sub>EE</sub> = 0 V		8 to 0	V
V <sub>EE</sub>	NECL Mode Power Supply	V <sub>CC</sub> = 0 V		-8 to 0	V
V <sub>I</sub>	PECL Mode Input Voltage NECL Mode Input Voltage	V <sub>EE</sub> = 0 V V <sub>CC</sub> = 0 V	V <sub>I</sub> ≤ V <sub>CC</sub> V <sub>I</sub> ≥ V <sub>EE</sub>	6 to 0 -6 to 0	V
I <sub>out</sub>	Output Current	Continuous Surge		50 100	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 SOIC-8	190 130	°C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44 ± 5%	°C/W
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ± 5%	°C/W
T <sub>sol</sub>	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## MC100LVEL12

**Table 3. LVPECL DC CHARACTERISTICS** ( $V_{CC} = 3.3\text{ V}$ ;  $V_{EE} = 0.0\text{ V}$  (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current		17	24		17	24		18	25	mA
$V_{OH}$	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
$V_{OL}$	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
$V_{IH}$	Input HIGH Voltage	2135		2420	2135		2420	2135		2420	mV
$V_{IL}$	Input LOW Voltage	1490		1825	1490		1825	1490		1825	mV
$I_{IH}$	Input HIGH Current			150			150			150	mA
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .
2. Outputs are terminated through a 50  $\Omega$  resistor to  $V_{CC} - 2.0\text{ V}$ .

**Table 4. LVNECL DC CHARACTERISTICS** ( $V_{CC} = 0.0\text{ V}$ ;  $V_{EE} = -3.3\text{ V}$  (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current		17	24		17	24		18	25	mA
$V_{OH}$	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
$V_{OL}$	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
$V_{IH}$	Input HIGH Voltage	-1165		-880	-1165		-880	-1165		-880	mV
$V_{IL}$	Input LOW Voltage	-1810		-1475	-1810		-1475	-1810		-1475	mV
$I_{IH}$	Input HIGH Current			150			150			150	mA
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .
2. Outputs are terminated through a 50  $\Omega$  resistor to  $V_{CC} - 2.0\text{ V}$ .

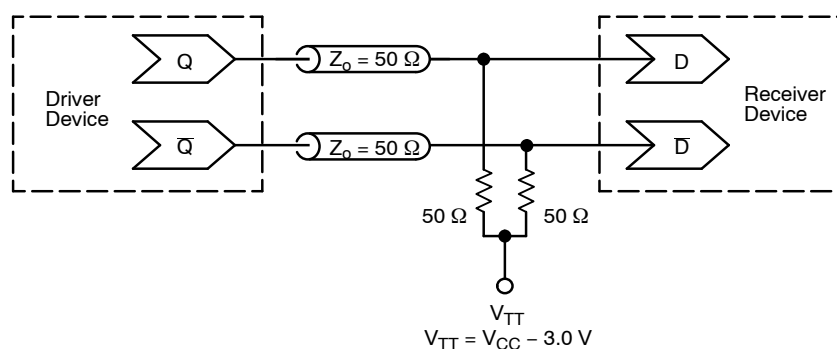
**Table 5. AC CHARACTERISTICS** ( $V_{CC} = 3.3\text{ V}$ ;  $V_{EE} = 0.0\text{ V}$  or  $V_{CC} = 0.0\text{ V}$ ;  $V_{EE} = -3.3\text{ V}$  (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{max}$	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
$t_{PLH}$ $t_{PHL}$	Propagation Delay to Output	310		580	310	445	580	320		590	ps
$t_{JITTER}$	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
$t_r$ $t_f$	Output Rise/Fall Times Q (20%–80%)	230	400	550	230	400	550	230	400	550	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1.  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .

**MC100LVEL12**



**Figure 2. Typical Termination for Output Driver and Device Evaluation**  
 (See Application Note [AND8020/D](#) – Termination of ECL Logic Devices)

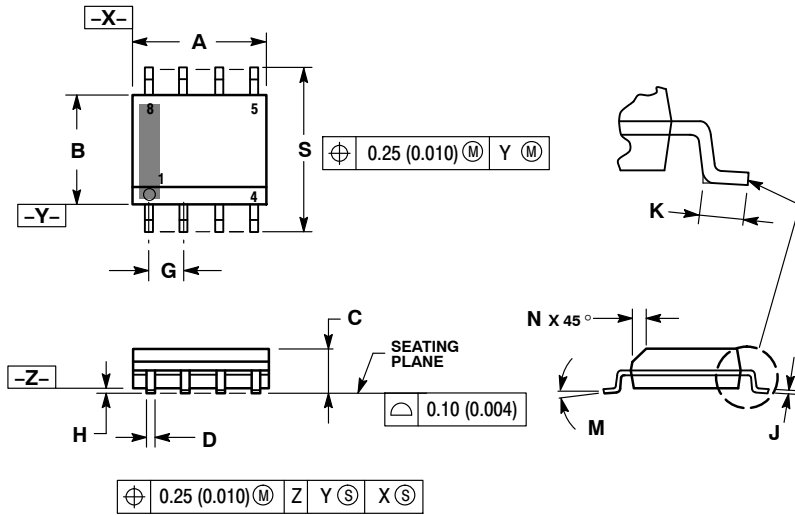
**Resource Reference of Application Notes**

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

**MC100LVEL12**

**PACKAGE DIMENSIONS**

**SOIC-8 NB**  
**D SUFFIX**  
CASE 751-07  
ISSUE AK

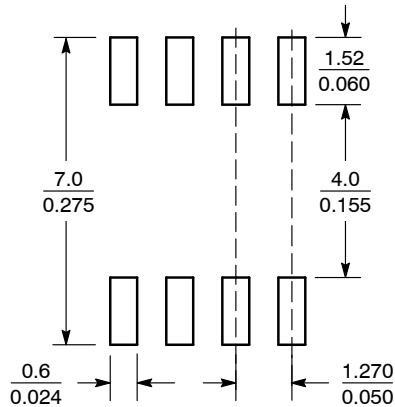


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

**SOLDERING FOOTPRINT\***



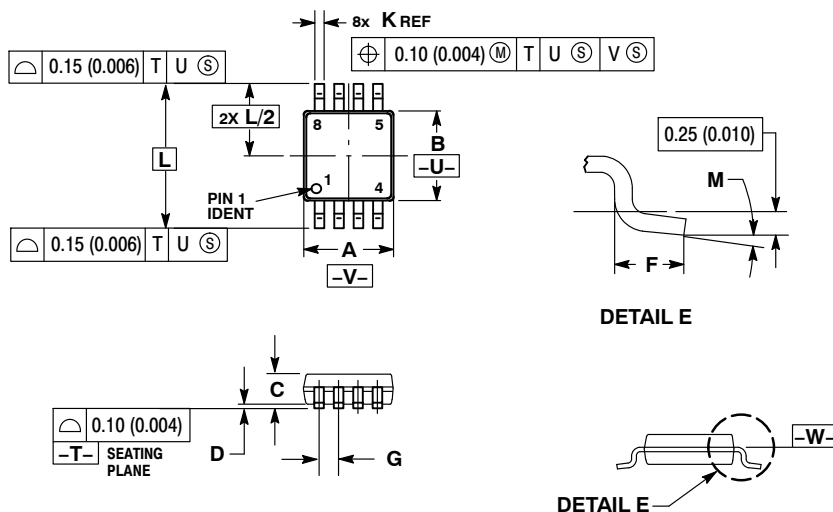
SCALE 6:1 (mm/inches)

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## MC100LVEL12

### PACKAGE DIMENSIONS

TSSOP-8  
DT SUFFIX  
CASE 948R-02  
ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -V-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

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